Product / Package Information

Package	LFCSP - Punched
Body Size (mm)	5 X 5 X 0.85 (3.1 EP)
Lead Count	16
Terminal Finish	100 Sn
MS Number	MS000522E

Environmental Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	2.31E-02	86.91	869100	37.48	374850
Thermosets	Epoxy & Phenol Resin	Proprietary	3.39E-03	12.78	127800	5.51	55121
Other inorganic materials	Carbon black	1333-86-4	8.22E-05	0.31	3100	0.13	1337
Subtotal			2.65 E-02	100.00	1000000	43.13	431308

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	3.20 E-02	97.50	975000	51.96	519571
Copper & its alloys	Iron	7439-89-6	7.70 E-04	2.35	23500	1.25	12523
Copper & its alloys	Zinc	7440-66-6	3.93 E-05	0.12	1200	0.06	639
Copper & its alloys	Phosphorus	7723-14-0	9.83 E-06	0.03	300	0.02	160
Subtotal			3.28 E-02	100.00	1000000	53.29	532894

Internal Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	7.15 E-04	100.0	1000000	1.16	11619

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	1.74 E-04	100.0	1000000	0.28	2826

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	5.16 E-04	99.0	990000	0.84	8394
Precious metals	Palladium	7440-05-3	5.21 E-06	1.0	10000	0.01	85
Subtotal			5.21 E-04	100.0	1000000	0.85	8479

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	6.66 E-04	100.0	1000000	1.08	10834

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	9.23 E-05	73.54	735400	0.15	1501
Other organic materials	Epoxy resin A	TS ref# 10013	9.23 E-06	7.35	73500	0.02	150
Others	Anhydride	TS ref# 10181	9.23 E-06	7.35	73500	0.02	150
Other organic materials	2,6-Diglycidyl phenyl allyl ether oligomer	Unassigned	3.69 E-06	2.94	29400	0.01	60
Other organic materials	Epoxy resin B	TS ref# 10237	3.69 E-06	2.94	29400	0.01	60
Others	Epoxy resin modifier	TS ref# 10038	3.69 E-06	2.94	29400	0.01	60
Others	Anhydride	TS ref# 10180	3.69 E-06	2.94	29400	0.01	60
Subtotal			1.26 E-04	100.0	1000000	0.20	2041

	Weight (g)	Percentage (%)	PPM
Package Totals	**6.15 E-02**	**100**	**1000000**

Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.

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